

SM1150 LDMOS TRANSISTOR

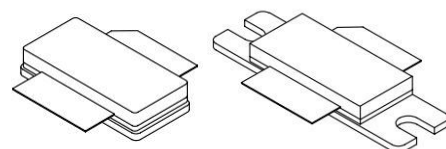
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Rev. Preliminary Datasheet

1000MHz-1100MHz, 500W, 50V High Power RF LDMOS FETs

- Typical Performance (In Demo Fixture): $P_{-1dB} = 520$ Watts @ 1100 MHz, $V_{DD} = 50$ Volts, $I_{DQ} = 100$ mA, pulse width = 10 μ s, Duty cycle = 1%.

Frequency	Gp (dB)	P_{-1dB} (W)	$\eta_D@P_{-1}$ (%)	P_{-3dB} (W)	$\eta_D@P_{-3}$ (%)
1100 MHz	16.8	520	57	560	60

- Capable of Handling 10:1 VSWR, @ 50Vdc, 1100 MHz, 520 Watts pulsed output
Power Designed for Enhanced Ruggedness.
- Typical $P_{out} = 560$ Watts @ 3 dB Compression Point, pulsed @ 1100 MHz



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SM1150E

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DSS}	+110	Vdc
Gate--Source Voltage	V_{GS}	-10 to +10	Vdc
Operating Voltage	V_{DD}	+52	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	+150	°C
Operating Junction Temperature	T_J	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case Case Temperature 80°C, 520 W pulsed, $V_{DD}=50$ Vdc, $I_{DQ} = 100$ mA	$R_{\theta JC}$		°C/W

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22--A114)	Class 2

Table 4. Electrical Characteristics ($T_A = 25$ °C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
DC Characteristics					
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 85V$, $V_{GS} = 0$ V)	I_{DSS}	—	—	10	μ A
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 50$ V, $V_{GS} = 0$ V)	I_{DSS}	—	—	1	μ A
Gate--Source Leakage Current ($V_{GS} = 6$ V, $V_{DS} = 0$ V)	I_{GSS}	—	—	1	μ A
Gate Threshold Voltage ($V_{DS} = 50V$, $I_D = 300$ μ A)	$V_{GS(th)}$	—	1.8	—	V
Gate Quiescent Voltage	$V_{GS(Q)}$	—	2.75	—	V

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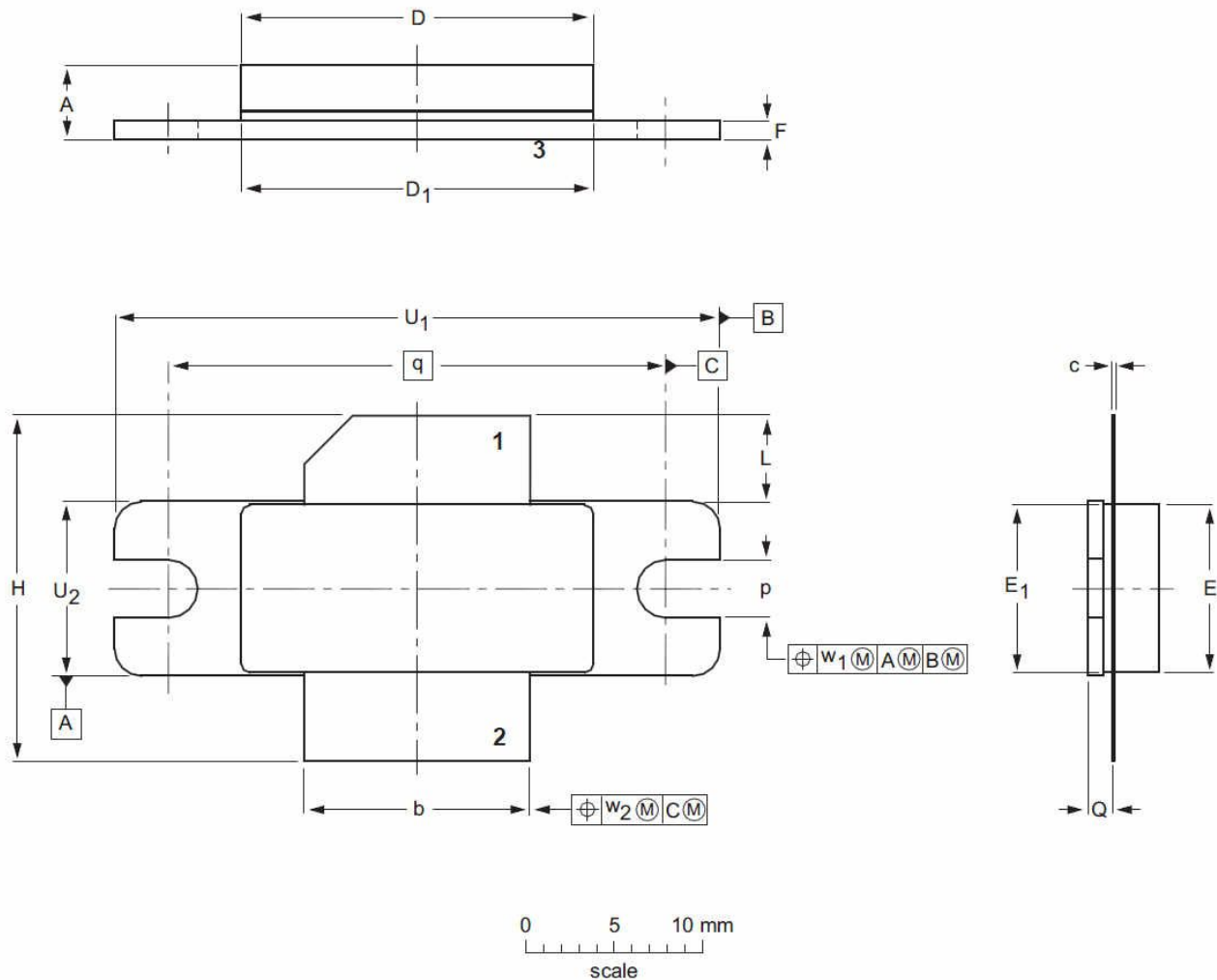
(V _{DD} = 50 V, I _D = 100 mA, Measured in Functional Test)					
Functional Tests (In Demo Test Fixture, 50 ohm system) V _{DD} = 50 Vdc, I _{DQ} = 100 mA, f = 1100 MHz, pulsed signal Measurements.					
Power Gain	G _p	——	16.8	——	dB
Drain Efficiency@P3dB	η _D	——	60	——	%
1 dB Compression Point	P _{-1dB}	——	520	——	W
3dB Compression Point	P _{-3dB}	——	560	——	W
Input Return Loss	IRL	——	-10	——	dB

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Package Outline

Flanged ceramic package; 2 mounting holes; 2 leads



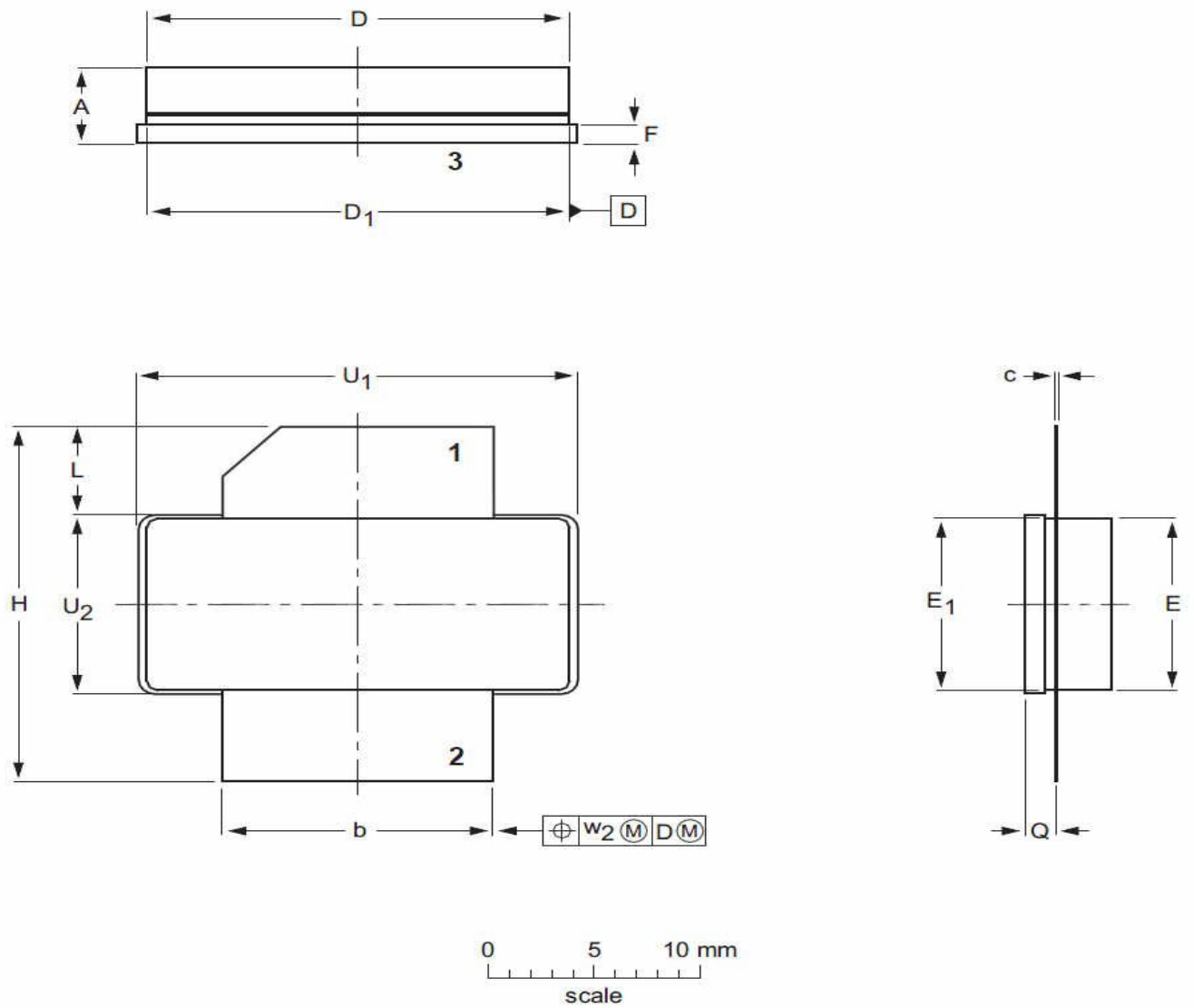
UNIT	A	b	c	D	D ₁	E	E ₁	F	H	L	p	Q	q	U ₁	U ₂	W ₁	W ₂
mm	4.72	12.83	0.15	20.02	19.96	9.50	9.53	1.14	19.94	5.33	3.38	1.70	27.94	34.16	9.91	0.25	0.51
	3.43	12.57	0.08	19.61	19.66	9.30	9.25	0.89	18.92	4.32	3.12	1.45					
inches	0.186	0.505	0.006	0.788	0.786	0.374	0.375	0.045	0.785	0.210	0.133	0.067	1.100	1.345	0.390	0.01	0.02
	0.135	0.495	0.003	0.772	0.774	0.366	0.364	0.035	0.745	0.170	0.123	0.057					

OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-B2E					03/12/2013

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Earless flanged ceramic package; 2 leads



UNIT	A	b	c	D	D ₁	E	E ₁	F	H	L	Q	U ₁	U ₂	W ₂
mm	4.72	12.83	0.15	20.02	19.96	9.50	9.53	1.14	19.94	5.33	1.70	20.70	9.91	0.25
	3.43	12.57	0.08	19.61	19.66	9.30	9.25	0.89	18.92	4.32	1.45	20.45	9.65	
inches	0.186	0.505	0.006	0.788	0.786	0.374	0.375	0.045	0.785	0.210	0.067	0.815	0.390	0.010
	0.135	0.495	0.003	0.772	0.774	0.366	0.364	0.035	0.745	0.170	0.057	0.805	0.380	

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